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PAM4 Analysis, SAS 4.0 Analysis, USB 3.1 Compliance, DDR Memory Validation, and Digital Power Management and Integrity Test Capabilities to be Showcased at DesignCon 2017

Industry-Leading High Speed Test Technologies Fundamental to New Serial Data Bus Testing and Signal Integrity Analysis

Chestnut Ridge, NY and Santa Clara, CA, January 31, 2017 – Teledyne LeCroy, a longtime Diamond Sponsor of DesignCon, will once again showcase the latest innovations in test technology on the exhibition floor, Booth 733 in Santa Clara, February 1-2. Product exhibits include the HDO family of 12-bit high definition oscilloscopes; PAM4 signal analysis; digital power management IC, power sequencing, and power-integrity testing; USB 3.1 and Power Delivery compliance test over Type-C; MIPI M-PHY physical- and protocol-layer test; PCI Express Tx/Rx compliance; DDR compliance and debug capabilities; and the world's first SAS 4.0 Analyzer Platform.

Booth demonstrations will include live testing of a 28-Gbaud PAM4 SERDES to the OIF CEI-56G-VSR-PAM4 specification. The booth will also feature a unique hands-on station at which attendees may interact with the latest in protocol analysis equipment. They can also experience the high-definition HDO9000 oscilloscope, featuring the industry's most intuitive touch-screen interface.

Technology Talks

In addition to the booth demonstrations, Teledyne LeCroy technical experts will contribute to many conference sessions. Dr. Eric Bogatin speaks on several topics including "Electrical Characterization of PCBs and Related Interconnects at Frequencies Up to 50 GHz" and "A New Characterization Technique for Glass Weave Skew". Peter Pupalais presents papers on "The Fastest PAM4 Signal Ever Generated", "A Generic Test Tool for Power Distribution Networks", and "Understanding Vertical Resolution in Oscilloscopes".

Other significant contributions to the technical conference include "Digital Power Management and Power Integrity Analysis and Testing", presented in the Chiphead Theater on the expo floor on Wednesday at 3 PM by Ken Johnson and Peter Pupalais. Dr. Martin Miller participates in "The Case of the Closing Eyes - 400G Signal Integrity", a panel with industry jitter experts on Tuesday at 4:45 pm.

A complete schedule of speakers and topics can be found at teledynelecroy.com/designcon.

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About DesignCon

DesignCon, produced by UBM Canon, is the world's premier conference for chip, board and systems design engineers in the high-speed communications and semiconductor communities. DesignCon, created by engineers for engineers, takes place annually in Silicon Valley and remains the largest gathering of chip, board and systems designers in the country. This four-day technical conference and expo combines technical paper sessions, tutorials, industry panels, product demos and exhibits from the industry's leading experts and solutions providers. More information is available at: <http://www.designcon.com/santaclara/>. DesignCon is organized by UBM Americas, a part of UBM plc (UBM.L), an Events First marketing and communications services business. For more information, visit ubmamericas.com.

About Teledyne LeCroy

Teledyne LeCroy is a leading manufacturer of advanced oscilloscopes, protocol analyzers, and other test instruments that verify performance, validate compliance, and debug complex electronic systems quickly and thoroughly. Since its founding in 1964, the Company has focused on incorporating powerful tools into innovative products that enhance "Time-to-Insight". Faster time to insight enables users to rapidly find and fix defects in complex electronic systems, dramatically improving time-to-market for a wide variety of applications and end markets. Teledyne LeCroy is based in Chestnut Ridge, N.Y. For more information, visit Teledyne LeCroy's website at teledynelecroy.com.

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